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Contents

vii *Authors*
ix *Conference Committee*

SESSION 1 NOVEL OPTICAL WAVEGUIDE AND INTERCONNECT TECHNOLOGIES

- 10109 02 **Low-loss characteristics of a multimode polymer optical circuit at 1.3- μm wavelength on printed circuit board (Invited Paper)** [10109-1]
- 10109 03 **Future of high-speed short-reach interconnects using clad-dielectric waveguide (Invited Paper)** [10109-2]
- 10109 04 **Optimization of optical losses in waveguide component manufacturing (Invited Paper)** [10109-3]
- 10109 05 **Evaluation of hybrid polymers for high-precision manufacturing of 3D optical interconnects by two-photon absorption lithography (Invited Paper)** [10109-4]

SESSION 2 NANOPHOTONICS FOR OPTICAL INTERCONNECTS

- 10109 07 **Design of signal router employing optical switching in MIM plasmonic waveguides** [10109-6]
- 10109 08 **Understanding the source of dielectric loss in Titania/polypropylene nanocomposites up to 220 GHz** [10109-7]

SESSION 3 HYBRID INTEGRATED OPTICAL LINK MODULES

- 10109 0B **CWDM transceiver for mid-board optics (Invited Paper)** [10109-10]
- 10109 0C **A mechanical-optical interface for 25+ Gbps VCSEL/PD fiber coupling** [10109-11]
- 10109 0D **WDM mid-board optics for chip-to-chip wavelength routing interconnects in the H2020 ICT-STREAMS (Invited Paper)** [10109-12]
- 10109 0E **VCSEL-based optical transceiver module for high-speed short-reach interconnect (Invited Paper)** [10109-13]
- 10109 0F **PAM4 silicon photonic microring resonator-based transceiver circuits (Invited Paper)** [10109-14]

SESSION 4 ELECTRICAL-OPTICAL PCB TECHNOLOGIES

- 10109 0H **Pluggable multimode edge connector for glass-based electro-optical circuit boards (EOCB)** [10109-16]
- 10109 0I **Accurate core position control in polymer optical waveguides using the Mosquito method for three-dimensional optical wiring** [10109-17]
- 10109 0J **Insertion loss study for panel-level single-mode glass waveguides** [10109-18]

SESSION 5 OPTICAL INTERCONNECT DEVICES AND MODULATORS

- 10109 0M **VCSEL design and integration for high-capacity optical interconnects (Invited Paper)** [10109-21]
- 10109 0O **One-dimensional photonic crystal slot waveguide for silicon-organic hybrid electro-optic modulators** [10109-23]

SESSION 6 FIBER OPTICS AND MICRO-OPTICS INTEGRATION

- 10109 0R **Fiber bundle probes for interconnecting miniaturized medical imaging devices** [10109-26]
- 10109 0S **Multimode fiber for high-density optical interconnects (Invited Paper)** [10109-27]
- 10109 0T **Micro/nanoscale self-aligned optical couplings of the self-organized lightwave network (SOLNET) formed by two-photon photochemistry** [10109-28]

SESSION 7 OPTICAL INTERCONNECT SYSTEMS

- 10109 0V **Optical CAM architecture for address lookup at 10 Gbps** [10109-30]
- 10109 0W **Modeling, simulation and measurement of a bidirectional optical interconnection system for industrial applications** [10109-31]
- 10109 0X **A programmable Si-photonics node for SDN-enabled Bloom filter forwarding in disaggregated data centers** [10109-32]
- 10109 0Y **Converged photonic data storage and switch platform for exascale disaggregated data centers** [10109-33]

SESSION 8 PICS FOR OPTICAL INTERCONNECTS

- 10109 0Z **Thermo-optic tunable grating structure for coupler and radiator applications in silicon** [10109-34]

SESSION 9 HYBRID DEVICE INTEGRATION APPROACHES FOR SILICON PHOTONICS CHIPS

- 10109 14 **Thick-SOI Echelle grating for any-to-any wavelength routing interconnection in multi-socket computing environments** [10109-39]
- 10109 15 **Hybrid integration of laser source on silicon photonic integrated circuit for low-cost interferometry medical device** [10109-40]

POSTER SESSION

- 10109 19 **Modeling of all-optical 3x8 line decoder using optical Kerr effect in plasmonic metal-insulator-metal waveguides** [10109-44]

Authors

Numbers in the index correspond to the last two digits of the seven-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first five digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Aalto, T., 14	Hyer, Maynard G., 04
Alexoudi, T., 14	Ide, Satoshi, 0E
Amano, Takeru, 02	Ishigure, Takaaki, 0I
Arndt-Staufenbiel, Norbert, 0R	Kanellos, G. T., 0D, 14
Bae, H. M., 03	Kang, Geumbong, 0Z
Baets, Roel, 15	Karlsson, Magnus, 0M
Beausoleil, Raymond, 0F	Kerr, Terrence, 0C
Bedi, Amna, 07, 19	Kim, Jeongyoon, 0Z
Bickham, Scott R., 0S	Kim, Jong-Hun, 0Z
Bogdan, M., 0X	Kim, Seong-Hwan, 0Z
Brimont, A., 0X	Klein, J. J., 05
Brusberg, Lars, 0H	Komiyama, Takeshi, 0E
Butler, Douglas L., 0H	Kraft, J., 0X
Carroll, Lee, 15	Krupp, A., 05
Chakravarty, Swapnajit, 0O	Kumar, Santosh, 07, 19
Chalk, Julie A., 0S	Kurtz, Dan, 0C
Chatzianagnostou, E., 0X	Kwon, S. W., 03
Chen, Ray T., 0O	Lang, K.-D., 0J
Cherchi, M., 14	Larsson, Anders, 0M
Childers, Darrell, 0B	Lee, Dae-Seong, 0Z
Christophliemke, Tobias, 0W	Lee, Harin, 0Z
Chung, Chi-Jui, 0O	Lee, J. Y., 03
Collins, Sean, 15	Lee, Yun-Ju, 08
Combs, Gregg, 0B	Lengyel, Tamas, 0M
Dabos, G., 14	Lewallen, Christopher P., 0H
Daikuhara, Osamu, 0E	Li, Cheng, 0F
Date, Kumi, 0I	Li, Yanlu, 15
Degroot, Jon V., 04	Lutz, Sharon, 0C
Devenport, Kent, 0B	Maniotis, P., 0V
Dorrestein, S., 0X	Marti, J., 0X
Duperron, Matthieu, 15	Marx, Sebastian, 0J, 0R
Fiorentino, Marco, 0F	Mathai, Sagi, 0B
Fitsios, D., 14	McClure, Randy L., 0H, 0S
Fortusini, Davide D., 0H	Megason, George, 0B
Frey, C., 0J	Miliou, A., 0X
Gruetzner, G., 05	Mitsolidou, C., 14
Grünberg, Olaf, 0W	Moore, David, 0B
Gustavsson, Johan S., 0M	Moralis-Pegios, M., 0X
Haglund, Emanuel P., 0M	Mori, Tatsuhiro, 0E
Haglund, Erik, 0M	Nawata, Hideyuki, 0T
Harjanne, M., 14	Neitz, M., 0J
Hastings, D. J., 0B	Neu, Marc, 0W
Herbsommer, Juan, 08	Nguyen, Dennis, 0R
Herbst, C., 0J	Noriki, Akihiro, 02
Herter, Jonas, 0R	O'Brien, Peter, 15
Hofmann, Jens, 0R	Oku, Hideki, 0E
Houbertz, R., 05	Overcash, Jerald L., 0H
Hsu, Julia, 08	Paap, Mark T., 0S
Hurley, William C., 0S	Palermo, Samuel, 0F

Pan, Zeyu, 00
Panotopoulos, George, 0B
Park, Hyo-Hoon, 0Z
Pitris, S., 0X, 14
Pitwon, R., 0Y
Pleros, N., 0D, 0V, 0X, 14
Rankin, Glenn, 0B
Rensing, Marc, 15
Ripumaree, Radawan, 0S
Rochracher, K., 0X
Röder-Ali, J., 0J
Rosenberg, Paul, 0B
Roshan-Zamir, Ashkan, 0F
Sanchis, P., 0X
Schleunitz, A., 05
Schoellner, Dirk, 0C
Schröder, Henning, 0J, 0R
Seyedi, M. Ashkan, 0F
Shepherd, Debra A., 04
Simpanen, Ewa, 0M
Singh, Lokendra, 07, 19
Song, H. I., 03
Sorin, Wayne, 0B
Stender, B., 05
Stübbe, Oliver, 0W
Subbaraman, Harish, 0O
Swatowski, Brandon W., 04
Syrivelis, D., 0X
Szczërba, Krzysztof, 0M
Tan, Mike, 0B
Tanaka, Kazuhiro, 0E
Tassiulas, L., 0X
Tekin, T., 0X
Terzenidis, N., 0V, 0X
Tsudome, Rie, 0E
Vagionas, C., 0X
Vysokinos, K., 0X
Wang, Binhao, 0F
Wang, K., 0Y
Wang, Ke, 0C
Wang, Mike, 0C
Weidner, W. Ken, 04
Westbergh, Petter, 0M
Womble, Michael D., 08
Worrall, A., 0Y
Wu, Chris, 0H
Xu, Xiaochuan, 0O
Yagisawa, Takatoshi, 0E
Yan, Hai, 0O
Yeo, Sanggu, 0Z
Yoo, Dongeun, 0Z
Yoshimura, Tetsuzo, 0T
Yu, Kunzhi, 0F
Zamora, Vanessa, 0R
Zanzi, A., 0X
Zhao, Yan, 15

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- 1 Novel Optical Waveguide and Interconnect Technologies
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- 2 Nanophotonics for Optical Interconnects
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- 3 Hybrid Integrated Optical Link Modules
Qi Wu, Corning Incorporated (United States)
- 4 Electrical-Optical PCB Technologies
Takaaki Ishigure, Keio University (Japan)
- 5 Optical Interconnect Devices and Modulators
Christopher T. Middlebrook, Michigan Technological University (United States)
- 6 Fiber Optics and Micro-Optics Integration
Brandon W. Swatowski, Dow Corning Corporation (United States)
- 7 Optical Interconnect Systems
Richard C. Pitwon, Seagate Systems (UK) Ltd. (United Kingdom)
- 8 PICs for Optical Interconnects
Ray T. Chen, The University of Texas at Austin (United States)
- 9 Hybrid Device Integration Approaches for Silicon Photonics Chips
Christian Koos, Karlsruher Institut für Technologie (Germany)